

0083-0865-2



#30/9
12/18/01
[Signature]

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF: :
Masashi GOTOH, et al. : EXAMINER: CUNEO, K.
SERIAL NO.: 09/119,626 :
RCE FILED: Herewith : GROUP ART UNIT: 2841
FOR: CIRCUIT BOARD HAVING :
BONDING AREAS TO BE
JOINED WITH BUMPS BY
ULTRASONIC BONDING

RECEIVED
DEC 11 2001
TC 2800 MAIL ROOM

PRELIMINARY AMENDMENT

12/19/01 ✓
ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Prior to further consideration of the above-identified application, please amend the application as follows:

IN THE CLAIMS

Please cancel Claims 7, 9, and 13-15 without prejudice or disclaimer.

Please add new Claims 16-18, as follows:

SL
E1
OT
16. (New) A chip part device comprising:
a circuit board having a plurality of bonding areas defined by conductive pattern; and
a chip element mounted on said circuit board, and having a plurality of bump
electrodes which are joined with said bonding areas by ultrasonic bonding,
wherein said circuit board includes at least two grooves defined by said conductive
pattern, and located approximate to one of said bonding areas to put the bonding area
therebetween.